SPECIFICATION OF MODULE

MODULE NO：ZC-126001-0131

RoHS Complaint Product

Customer Approval:

☐ **Accept** ☐ **Reject**

ZOYO FOCUS	SIGNATURE	DATE
PREPARED BY	JYQ	2024.10.14
CHECKED BY	YG	2024.10.14
APPROVED BY		

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Hangzhou ZoYo Chuxian Intelligent Techonology Co.,Ltd.
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Sample Version	Doc. Version	DATE	DESCRIPTION	CHECKED BY
01	A	2024.10.14	First Release.	YG

1. GENERAL DESCRIPTION:

ZC - 1260 01 - 0131
① ② ③ ④

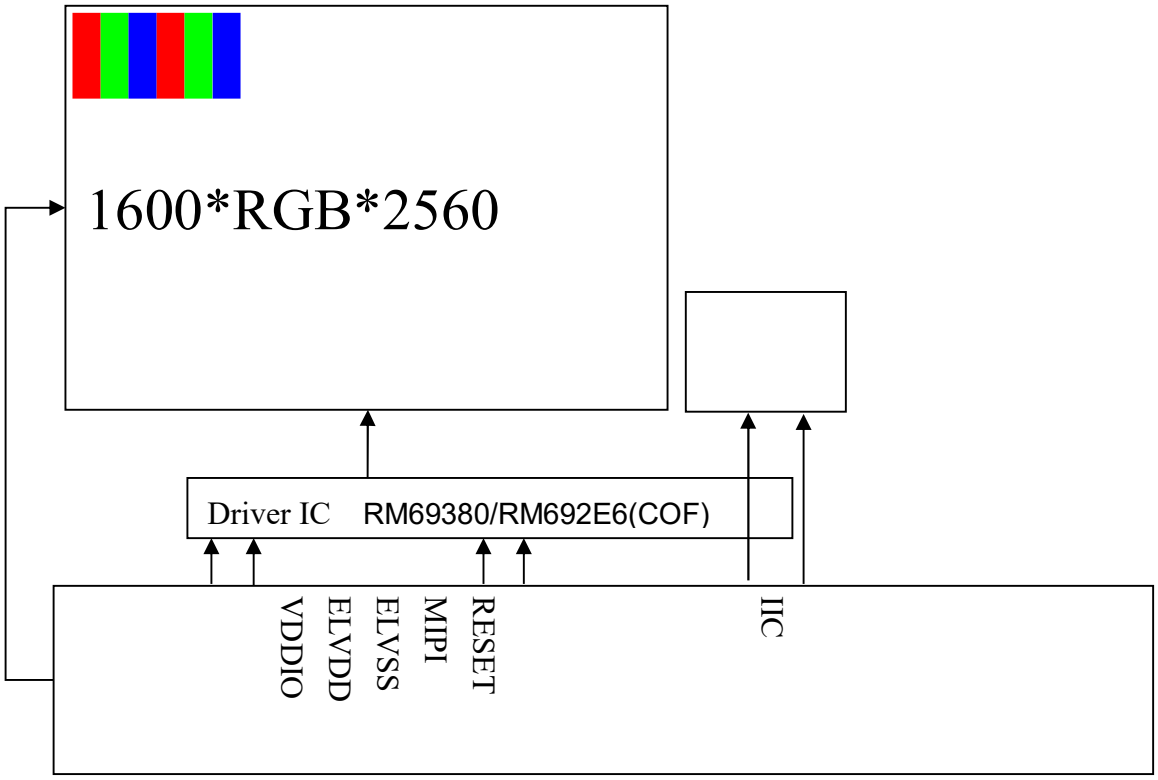
① ZOYO Focus Brand
② Display size: 12.6inch
③ LCM serial NO.
④ serial NO.

2. MECHANICAL SPECIFICATIONS:

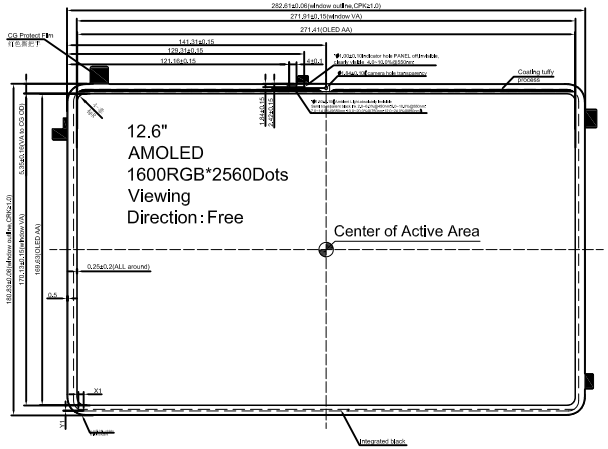
ITEM	SPECIFICATION	Remark
Module Outline Dimension(W x H x D)(mm)	275.411(W)×175.232(H)×1.659(D)	
Active Area(mm)	271.4112(H)×169.632(V)	
Pixel Pitch (um)	106.02x106.02	
Resolution(dot)	1600(H)×2560(V)	-
Driver IC(Type)	RM69380/RM692E6(COF)	-
Touch IC	GT7986P	
Display Mode	AMOLED	-
Interface	MIPI	
Color Depth	16.7M	-
Luminance	400 (TYP.)	cd/m²
Viewing Direction	ALL	-

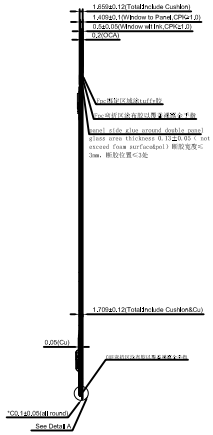
*See attached drawing for details.

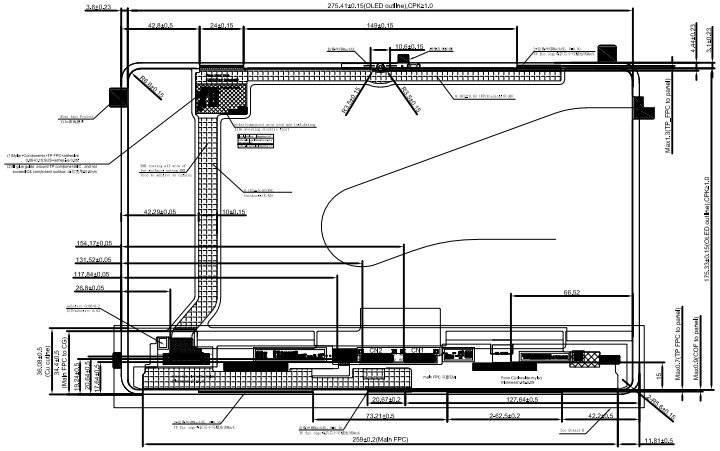
3.BLOCK DIAGRAM:

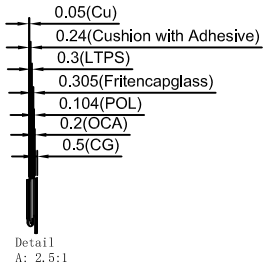


Ver	Amendment	Sign	Date
A	First Issue	DU	2024 1012

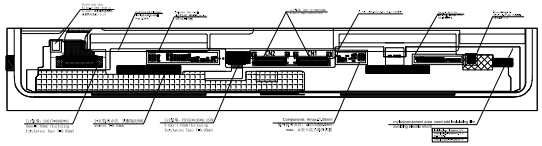








Detail
A: 2.5:1



Detail
B: 1:1

	CN2
PIN	Symbol
1	ELVSS
2	ELVSS
3	ELVSS
4	ELVSS
5	ELVSS
6	NC
7	ELVDD
8	ELVDD
9	ELVDD
10	ELVDD
11	ELVDD
12	ELVDD
13	ELVDD
14	NC
15	VDD_3.3V
16	VDD_3.3V
17	VDD_3.3V
18	VDD_3.3V
19	NC
20	GND
21	GND
22	GND
23	Bist_Enable
24	NC
25	NC
26	NC
27	MTP_PWR_L
28	NC
29	NC
30	PCD_L
31	NC
32	NC
33	RESX
34	NC
35	TE_L
36	GND
37	MIPI_D3N_R
38	MIPI_D3P_R
39	GND
40	MIPI_D2N_R
41	MIPI_D2P_R
42	GND
43	MIPI_CLKN_R
44	MIPI_CLKP_R
45	GND
46	MIPI_D1N_R
47	MIPI_D1P_R
48	GND
49	MIPI_D0N_R
50	MIPI_D0P_R
51	GND

Top View

Side view

Bottom View

Size	12.6Inch	Interface	MIPI
Resolution Ratio	1600x2560	Power Supply	3.3V
LCD Type	■ Rigid AMOLED ☐ Tranflective ☐ Reflective	Connection Mode	☐ FPC Plug-In ☐ FPC Soldering ■ Connector
Display Mode	■ LTPS ☐ LTPO	Driver IC TP IC	RM69380&RM692E6(COF)/GT7986P
Display Direction	☐ 6 ☐ 12 ☐ 3 ☐ 9 ■ Free	Operation Temperature	-20~+60
Contrast Ratio	100000:1	Storage Temperature	-30~+80
Luminance	400Typ. 360 Min.	Environmental Requirements	■ RoHS-2.0 ☐ REACH
Uniformity	70% Min.	Unmarked Tolerance	±0.2mm

PIN	Symbol(CN1)	PIN	Symbol	PIN	Symbol	PIN	Symbol	PIN	Symbol
1	NC	13	TSP_SDA	25	MIPI_CLKN_L	37	1.8V	49	NC
2	NC	14	TSP_SCL	26	MIPI_CLKP_L	38	1.8V	50	ELVSS
3	GND	15	TP IC CLK	27	GND	39	1.8V	51	ELVSS
4	TP_Report_EN	16	TSP_1.8V	28	MIPI_D1N_L	40	ID0		
5	TP_RST	17	TSP_1.8V	29	MIPI_D1P_L	41	ID1		
6	TP_INT_Sensorhub	18	GND	30	GND	42	NC		
7	TP_INT for AP	19	MIPI_D3N_L	31	MIPI_D0N_L	43	E_AVDD		
8	TP_SPI_CS0	20	MIPI_D3P_L	32	MIPI_D0P_L	44	NC		
9	TP_SPI_SCK	21	GND	33	GND	45	GND		
10	TP_SPI_MOSI	22	MIPI_D2N_L	34	ERR_FG	46	AVDD		
11	TP_SPI_MISO	23	MIPI_D2P_L	35	EL_12C_SCL	47	Swire		
12	GND	24	GND	36	EL_12C_SDA	48	NC		

Drawn	DU
Checked	HONG
Approved	
CSR Approved	
Customer No:	
Scale 1:1	
Sheet 1 Of 1	

TITLE

MODULE SPEC

Drawing No: ZC-126001-0131

Project No:

杭州中有触显智能科技
Hangzhou ZoYo Chuxian Intelligent Techonology

5. MAIN FPC PIN DESCRIPTION:

Pin No (CN1).	Symbol	I/O	Description	Note
1	NC	-	No connect.	
2	NC	-	No connect.	
3	GND	P	Ground.	
4	TP_Report_EN	I	Reserve pin ,If not used, please open this pin.	
5	TP_RST	I	Reset pin for touch, active low.	
6	TP_INT_Sensorhub	I	Reserve pin ,If not used, please open this pin.	
7	TP_INT for AP	I	Interrupt pin for Touch.	
8	TP_SPI_CS0	I	SPI Chip select pin for TP.	
9	TP_SPI_SCK	I	SPI Clock pin for TP.	
10	TP_SPI_MOSI	I	SPI MOSI pin for TP spi.	
11	TP_SPI_MISO	I	SPI MISO pin for TP spi.	
12	GND	P	Ground.	
13	TSP_SDA	I	Reserve pin，please open this pin.	
14	TSP_SCL	I	Reserve pin，please open this pin.	
15	TP IC CLK	I	Reserve pin，please open this pin.	
16	TSP_1.8V	P	TP IOVCC power.	
17	TSP_3.3V	P	TP AVDD power.	
18	GND	P	Ground.	
19	MIPI_D3N_L	I	DSI-D3- of Master IC MIPI.	
20	MIPI_D3P_L	I	DSI-D3+ of Master IC MIPI.	
21	GND	P	Ground.	
22	MIPI_D2N_L	I	DSI-D2- of Master IC MIPI.	

PinNo (CN1).	Symbol	I/O	Description	Note.
23	MIPI_D2P_L	I	DSI-D2+ of Master IC MIPI.	
24	GND	P	Ground.	
25	MIPI_CLKN_L	I	DSI-CLK- of Master IC MIPI.	
26	MIPI_CLKP_L	I	DSI-CLK+ of Master IC MIPI.	
27	GND	P	Ground.	
28	MIPI_D1N_L	I	DSI-D1- of Master IC MIPI.	
29	MIPI_D1P_L	I	DSI-D1+ of Master IC MIPI.	
30	GND	P	Ground.	
31	MIPI_D0N_L	I	DSI-D0- of Master IC MIPI.	
32	MIPI_D0P_L	I	DSI-D0+ of Master IC MIPI.	
33	GND	P	Ground.	
34	ERR_FG	O	Output pin used to monitor display driver s tate and error status of MIPI’ s HSDT.	
35	EL_I2C_SCL	I/O	(I2C) SCL clock I/O pin for PMIC.	
36	EL_I2C_SDA	I/O	(I2C) SCL data I/O pin for PMIC.	
37-39	1.8V	P	VDDI for DDIC.	
40	ID0	O	ID Pin，Output pin，internally connect 1.8 V，If not used，please open this Pin.	
41	ID1	O	ID Pin，Output pin，internally connect GN D，If not used，please open this Pin.	
42	NC	-	No connect.	
43	E_AVDD	P	Power supply for DDIC Analog system.	
44	NC	-	No connect.	
45	GND	P	Ground.	
46	AVDD EN	I	Power IC enable control pin.	
47	Swire	I	Swire protocol setting pin of power IC.	
48	NC	-	No connect.	
49	NC	-	No connect.	
50-51	ELVSS	P	ELVSS for OLED.	

Connector Name/Designation	Interface Connector/Interface Card
Type Part Number	I-PEX 20718-051E-01
Mating Housing Part Number	FPC 51PIN 0.3Pitch

Note: I=Input; O=Output; P=Power; I/O=Input / Output

PinNo. (CN2)	Symbol	I/O	Description	Note.
1-5	ELVSS	P	ELVSS for OLED.	
6	NC	-	No connect.	
7-13	ELVDD	P	ELVDD for OLED.	
14	NC	-	No connect.	
15-18	VDD_3.3V	P	Power supply for DDIC Analog circuit.	
19	NC	-	No connect.	
20-22	GND	P	Ground.	
23	Bist_Enable		Reserve pin ,If not used, please open this pin.	
24-26	NC	-	No connect.	
27	MTP_PWR_L	P	MTP programming power supply pin (6V typical) Must be left open or connected to DVSS in normal condition.	
28-29	NC	-	No connect.	
30	PCD_L	I	Pins for PCD function, Reserve pin, Please o pen this pin.	
31-32	NC	-	No connect.	
33	RESX	I	Reset pin for DDIC, active low.	
34	NC	-	No connect.	
35	TE_L	I	Tearing effect output pin to synchronize MC U to frame writing.	
36	GND	P	Ground.	
37	MIPI_D3N_R	I	DSI-D3- of Slaver IC MIPI.	
38	MIPI_D3P_R	I	DSI-D3+ of Slaver IC MIPI.	
39	GND	P	Ground.	
40	MIPI_D2N_R	I	DSI-D2- of Slaver IC MIPI.	
41	MIPI_D2P_R	I	DSI-D2+ of Slaver IC MIPI.	
42	GND	P	Ground.	
43	MIPI_CLKN_R	I	DSI-CLK- of Slaver IC MIPI.	
44	MIPI_CLKP_R	I	DSI-CLK+ of Slaver IC MIPI.	
45	GND	P	Ground.	
46	MIPI_D1N_R	I	DSI-D1- of Slaver IC MIPI.	
47	MIPI_D1P_R	I	DSI-D1+ of Slaver IC MIPI.	
48	GND	P	Ground.	
49	MIPI_D0N_R	I	DSI-D0- of Slaver IC MIPI.	
50	MIPI_D0P_R	I	DSI-D0+ of Slaver IC MIPI.	
51	GND	P	Ground.	

Note: I=Input; O=Output; P=Power; I/O=Input / Output

6. ELECTRICAL CHARACTERISTICS

6.1 Absolute Maximum Ratings

Parameter	Symbol	Min.	Max.	Unit	Remarks
Analog/boost power voltage	VCI	-0.3	5.5	V	
I/O voltage	VDDIO	-0.3	5.5	V	
Operating temperature	Topr	-20	70	℃	
Storage temperature	Tstg	-40	80	℃	

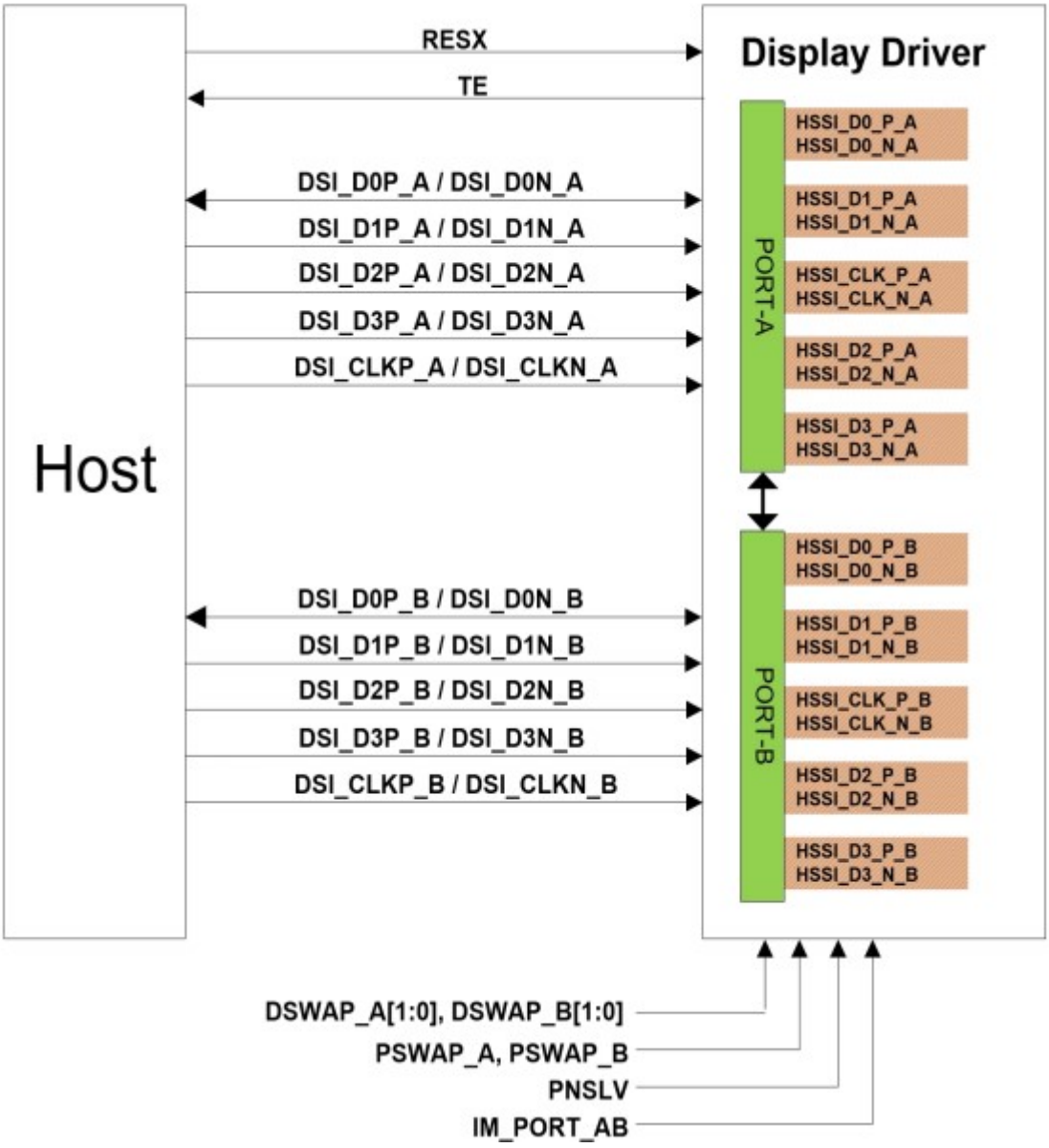
CTP

Work Mode	Item	Symbol	Min.	Max.	Uni	Remark
Sleep Mode	Current of TP_IOVCC	ITP_IOVCC	0.055	0.1	mA	Depend on TP IC model No gesture mode
	Current of TP_VCI	ITP_VCI	0.06	0.12	mA	Depend on TP IC model No gesture mode
Doze Mode	Current of TP_IOVCC	ITP_IOVCC	13	22	mA	Depend on TP IC model Idle mode
	Current of TP_VCI	ITP_VCI	4.87	10	mA	Depend on TP IC model Idle mode
Normal operation_x0002_ No finger	Current of TP_IOVCC	ITP_IOVCC	38	76	mA	Depend on TP IC model
	Current of TP_VCI	ITP_VCI	35	70	mA	Depend on TP IC model
Active (1 Finger)	Current of TP_IOVCC	ITP_IOVCC	38	90	mA	Depend on TP IC model
	Current of TP_VCI	ITP_VCI	35	70	mA	Depend on TP IC model
Active (5 Finger)	Current of TP_IOVCC	ITP_IOVCC	38	80	mA	Depend on TP IC model
	Current of TP_VCI	ITP_VCI	35	70	mA	Depend on TP IC model
Active (10 Finger)	Current of TP_IOVCC	ITP_IOVCC	38	80	mA	Depend on TP IC model
	Current of TP_VCI	ITP_VCI	35	70	mA	Depend on TP IC model

6.2 Electrical Characteristics

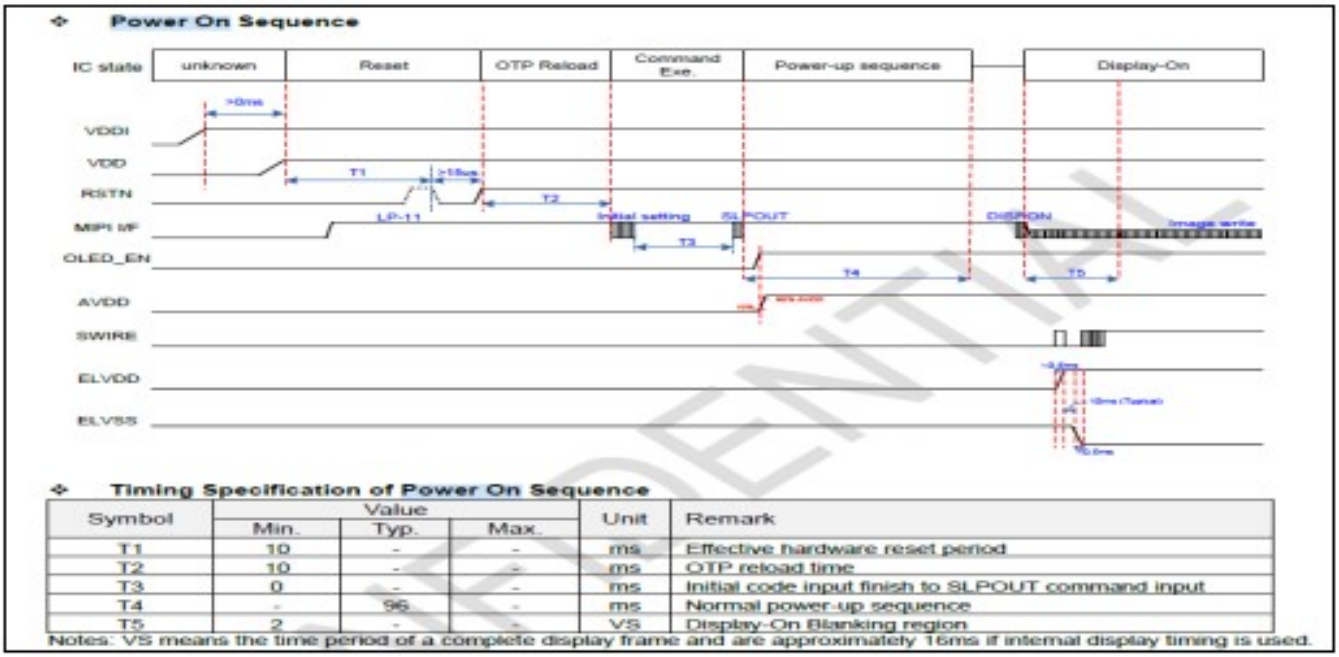
Item	Symbol	Min.	Typ.	Max.	Uni	Remark
TP Power supply	Touch _AVDD	2.7	3.3	3.4	V	Despond on the TSP IC
DDIC Power supply	VCI	2.7	3.3	3.6	V	
DDIC I/O Supply Voltage	VDDI	1.65	1.8	1.98	V	
TP Digital Power	DVDD	1.65	1.8	1.98	V	Despond on the TSP IC
DDIC Charge pumping Power	AVDD	6.3	6.4	6.5	V	
EL supply voltage	ELVDD	4.4	4.6	4.8	V	DC/DC output
EL supply voltage	ELVSS	-3.9	-3.8	-3.6	V	Controlled by DDIC
Input High Voltage	VIH	-	-	460	mV	MIPI HS
Input Low Voltage	VIL	-40	-	-	mV	MIPI HS
Input High Voltage	VIH	880	-	-	mA	MIPI LP
Input Low Voltage	VIL	-	-	550	mA	MIPI LP
Output High Voltage	VOH	1100	1200	1300	mA	MIPI LP
Output Low Voltage	VOL	-50	-	50	mA	MIPI LP
Frame Frequency	fFRAME	59	60	61	Hz	Command mode

6.3 MIPI-DSI Reference Circuit



7. RECOMMENDED OPERATING SEQUENCE

7.1 Display Power on Sequence



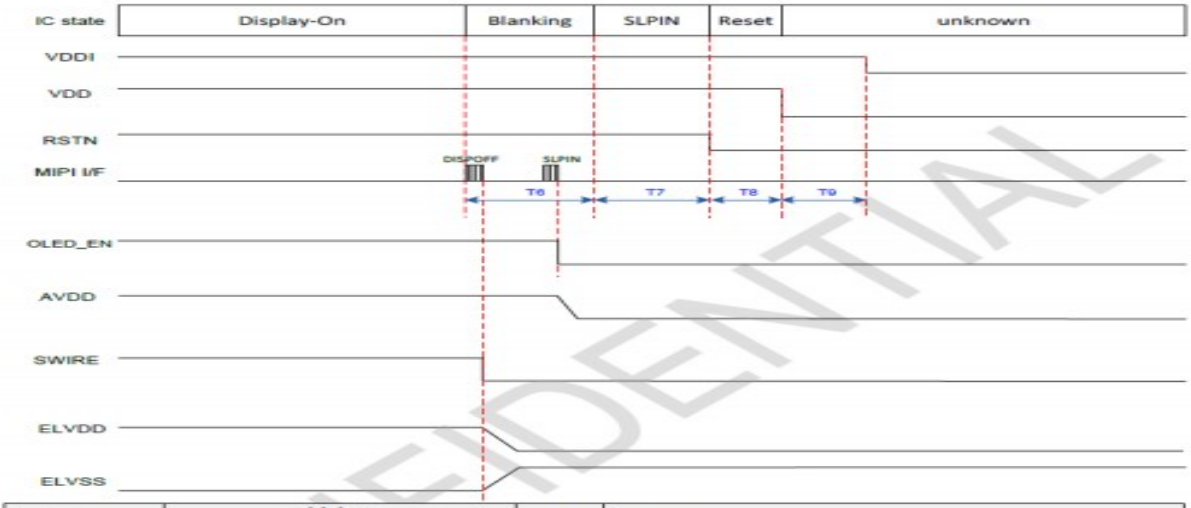
Timing Specification of Power On Sequence

Symbol	Value			Unit	Remark
	Min.	Typ.	Max.		
T1	10	-	-	ms	Effective hardware reset period
T2	10	-	-	ms	OTP reload time
T3	0	-	-	ms	Initial code input finish to SLPOUT command input
T4	-	96	-	ms	Normal power-up sequence
T5	2	-	-	VS	Display-On Blanking region

Notes: VS means the time period of a complete display frame and are approximately 16ms if internal display timing is used.

7.2 Display Power off Sequence

Power Off Sequence



Symbol	Value			Unit	Remark
	Min.	Typ.	Max.		
T6	2	-	-	VS	Display-Off blanking region
T7	1	-	-	VS	Blanking region
T8	1	-	-	ms	Effective hardware reset period
T9	2	-	-	ms	Power off period

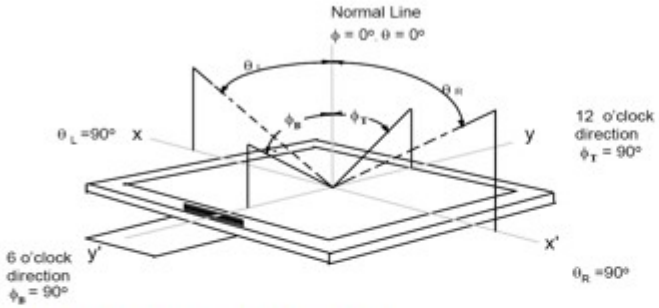
Notes: VS means the time period of a complete display frame and are approximately 16ms if internal display timing is used.

8. OPTICAL CHARACTERISTICS

The test of optical specifications shall be measured in a dark room (ambient luminance 1 lux and temperature = 25 2℃) with the equipment of the Luminance meter system (Goniometer system and TOPCON BM-5) and the test unit shall be located at an approximate distance 50cm from the LCD surface at a viewing angle of θ and Φ equal to 0 . We refer to θ Ø=0 (= θ 3) as the 3 o'clock direction (the "right"), θ Ø=90 (= θ 12) as the 12 o'clock direction ("upward"), θ Ø=180 (= θ 9) as the 9 o'clock direction ("left") and θ Ø=270(= θ 6) as the 6 o'clock direction ("bottom"). While scanning θ and/or Ø, the center of the measuring spot on the display surface shall stay fixed.

Item	Symbol	Condition	Min	Typ.	Max	Unit	Note
Viewing Angle	θL	Cr≥10	75	80	--	deg	Note 1
	θ_R		75	80	--		
	ψ_T		75	80	--		
	ψ_B		75	80	--		
Contrast Ratio	Cr	θ=0° FF=0°	100000	--	--	--	Note 2
Response Time	Tr+Tf		--	--	2	ms	Note 3
Color Coordinate of CIE1931	Wx	θ=0°	0.2825	0.3025	0.3225	--	Note 4
	Wy		0.286	0.306	0.326		
	Rx		0.664	0.684	0.704		
	Ry		0.295	0.315	0.335		
	Gx		0.195	0.235	0.275		
	Gy		0.686	0.726	0.766		
	Bx		0.108	0.138	0.168		
	By		0.015	0.045	0.075		
Uniformity	U		70	80	--	%	
Color Gamut			--	108	--	%	Note 5
OLED lifetime	LT95*(With out lens 600 nit)	At 25℃,with white color pattern	--	300	--	hrs	

Note 1:The definition of Viewing Angle
Refer to the graph below marked by θ and Φ.



Note2:ThedefinitionofContrastRatio

$$\text{Contrast Ratio(CR)} = \frac{\text{Luminance When LCD is at "White" state}}{\text{Luminance When LCD is at "Black" state}}$$

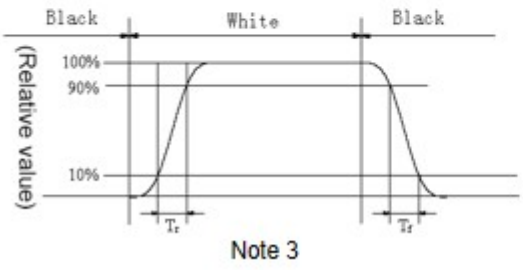
(Contrast Ratio is measured in optimum common electrode voltage)

Note3:DefinitionofResponse time.(Test LCD using RD80S or similar equipments):
The output sign also photo detector are measured when the input sign also are changed from "black" to "white" (Voltage falling time)and from "white" to "black" (Voltage rising time), respectively .The response time is defined as the time interval between the 10% and 90% of amplitudes . Refer to figures below.

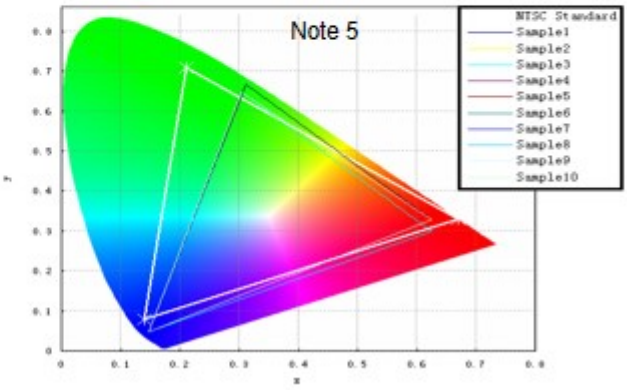
Note 4: Color Coordinates of CIE 1931
The test condition is at ILED=20mA and measured on the surface of LCD module at 25℃.
Measurement equipment:CS2000 or similar equipments
The Color Coordinate (CIE 1931) is the measurement of the center of the display shown in below figure.

Note 5: Definition of Color of CIE Coordinate and NTSC Ratio.

$$S = \frac{\text{area of RGB triangle}}{\text{area of NTSC triangle}} \times 100\%$$



Note 3



10. PACKAGE

TBD

11. STANDARD SPECIFICATION FOR RELIABILITY:

No	Test Items	Conditions	Testing standard
1	High temperature storage Test	Ta=+80℃, 128 hours	IEC60068-2-1:2007 GB2423.2-2008
2	Low temperature storage Test	Ta=-30℃, 128 hours	IEC60068-2-1:2007 GB2423.1-2008
3	High temperature operation Test	Ta=+60℃, 128 hours	IEC60068-2-1:2007 GB2423.2-2008
4	Low temperature operation Test	Ta=-20℃, 128 hours	IEC60068-2-1:2007 GB2423.1-2008
5	High temperature & humidity (storage Test)	Ta=+60℃, 90%RH max, 128 hours	IEC60068-2-78:2001 GB/T2423.3-2006
6	ESD Test	C=150pF, R=330 Ω, 5 points/panel Air:±8KV, 5 times; Contact: ±4KV, 5times; (Environment:15℃~35℃，30%~60%RH, 86Kpa~106Kpa)	EC61000-4-2:2001 GB/T17626.2-2006 Class C
7	Thermal shock Test	-30℃（60min/cycle）/+80℃（60min/cycle） 30cycle（2hr/cycle）	Start with cold temperature End with high temperature IEC60068-2-14:1984,GB2423. 22-2002

12. QUALITY LEVEL

12.1 AMOLED Module of Characteristic Inspection

The environmental condition and visual inspection shall be conducted as below:

12.1.1 Test conditions:

OLED is not light, cold white fluorescent lamp, illumination 1000 ±200lux; OLED lighting source shall not be higher than 200lux, with black background around.

12.1.2 Inspection distance:

the standard observation distance of all surfaces of the tested object is 30cm ± 5cm.

12.1.3 Inspection angle:

the angle between the product and the horizontal plane is 45 °, and the eyes are perpendicular to the inspection plane. During inspection, the product needs to rotate 45 ° up, down, left and right. The observation line of sight needs to be within the half section of the cone. The observation angle is 45 ° with the vertical axis of the product apex. The central axis of the cone must be standard and perpendicular to the product surface and pass through the fluorescent lamp; For non-conventional display defects (including but not limited to local bright lines or local floodlights), the observation angle is 75 degrees from the normal of the product surface; Full visual angle of appearance.

12.1.4 Inspection time:

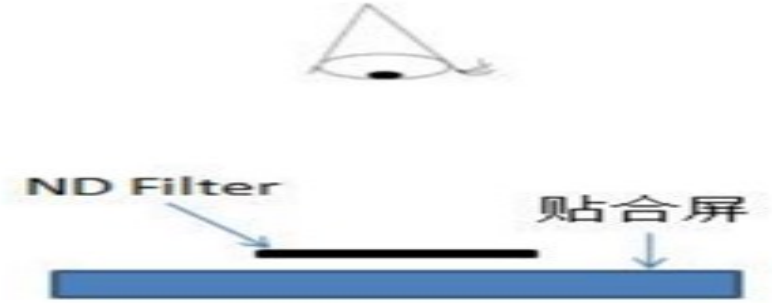
the inspection time without lighting is at least 10-12 seconds; The time of OLED lighting inspection for each picture is 1~3 seconds. If the defect is still not visible within the specified time, the inspection piece is deemed to be qualified.

12.1.5 Test temperature: room temperature 15-35 ℃, ambient humidity: 20-75% RH.

12.1.6 Inspection tools:

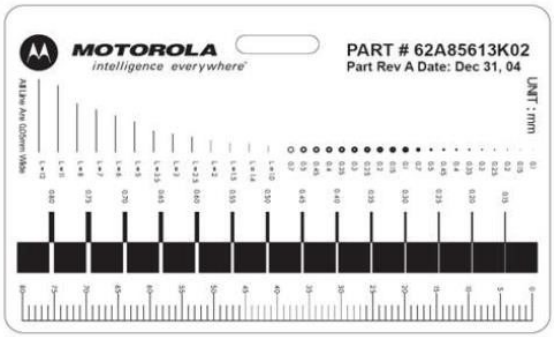
12.1.6.1 ND Filter:

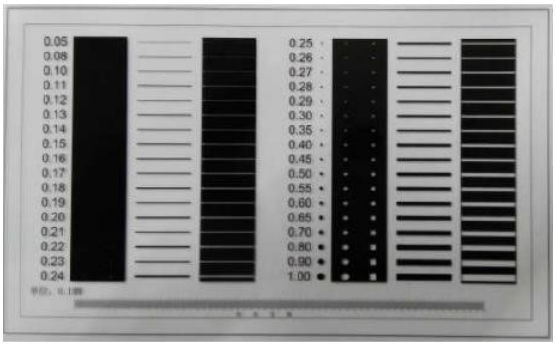
The ND Filter is placed at a distance of 2-3 cm above the defect for 2-3s to judge whether the defect is visible. As Figure below: (ND Filter is used to test mura isochromatic and light unevenness)

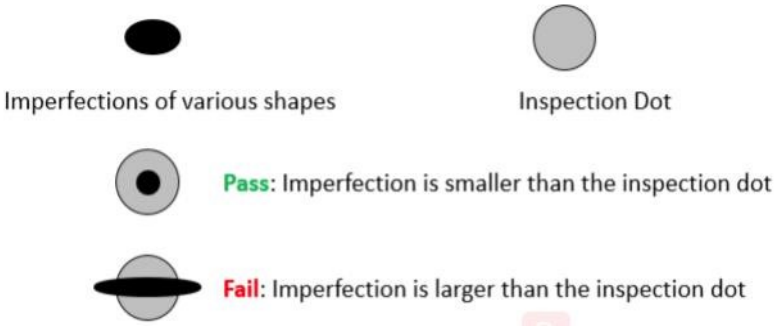


12.1.6.2 Point gauge (point gauge in the figure below is recommended), determination method: as shown in the figure, the point gauge film can cover is pass, and the point gauge film can not cover is Fail。For example, a maximum of 0.2mm same-color spot defect is allowed on the Class A surface, and the

pass that can be covered by 0.2mm on the film，The one that can be covered is Fail.







12.1.6.3 Microscopic examination: use 20-50 times adjustable microscope and 10-30 times test eyepiece.

12.1.6.4 Digital caliper: resolution 0.01mm.

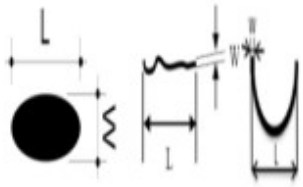
12.1.6.5 Projector: anime microscope, 3D projector.

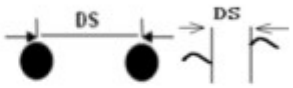
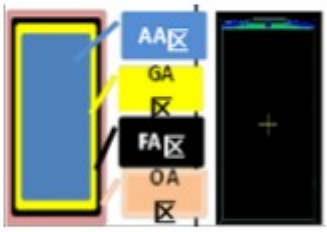
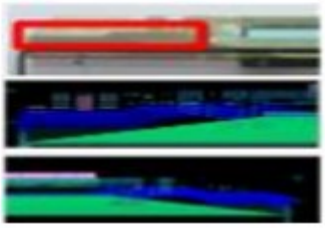
12.1.6.6 Judgment description:

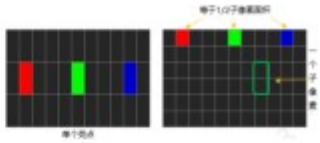
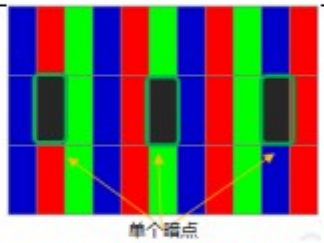
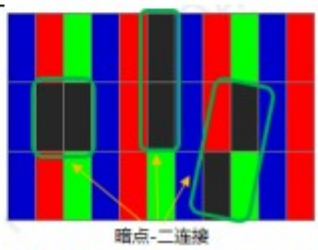
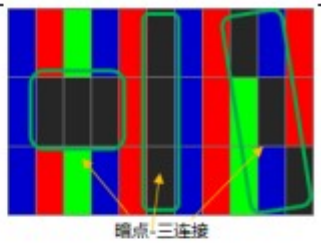
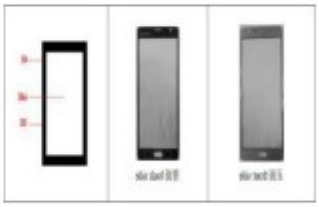
12.1.6.6.1 The measurement accuracy shall refer to the specification definition. When the measurement equipment accuracy is higher than the specification definition, the measured value needs to be rounded to the precision defined by the specificationthe. For example, the size of edge collapse is 0.20mm, and the thousandth is the reference position, which is rounded to 0.200mm~0.204mm is OK,>=0.205mm, it is judged as NG.

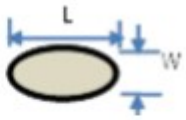
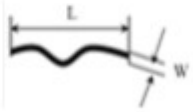
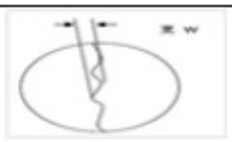
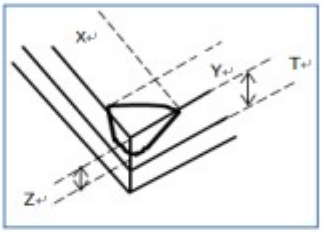
12.1.6.6.2 In addition to the tools used above, if additional inspection tools are needed to assist the judgment, they can only be carried out after the coordination of both parties.

12.1.6.6.3 Bad code and definition

Code and name		legend	explain
N	Number	-	Visually calculate the number; The statistics of the total number of defects does not include the completely "omitted" part. For the column defined as "omitted" and "omitted", it is not counted as the number of defects if it meets the requirements, otherwise it is calculated as an independent defect.
L	Length (mm)		Dot line distinguishing rule: L is the long side, W is the short side A. When L > 3W, handle as per line, otherwise handle as per point; B. When it is judged as line defect, S-shaped or C-shaped line appears, and the enclosed amount is less than 3/4 circle, it shall be treated as line defect; otherwise, it shall be treated as point defect, and the inner tangent circle shall simulate the size of point.
W	Width (mm)		
S	Area (^{mm2})	-	Surface gauge
D	Diameter (mm) D=(L+W)/2	-	Point diameter calculation: calculated by half of the sum of the long side and the short side, that is,

			D=(L+W)/2, where D represents the diameter of the point, L is the long side, and W is the short side;
H	Depth (mm)	-	Digital micrometer
DS	Distance (mm)		Distance between two points or between two lines
Schematic diagram of screen area			AA area: display area; GA area: GIP circuit area; FA area: Frit area; OA area: outside FA area
Leader area			Screen GIP circuit area, screen data circuit area
PAD Bangding District			COG/FOG Bonding alignment mark and Bonding Pad on LTPS substrate
PAD Non-state area			Screen test pad, cutting area and lead-free area on LTPS substrate
CT crimping area			Pin end screen test pad

Highlights		A single sub-pixel (or red, or green, or blue) of one pixel is called a point; The definition of bright spot is that in the environment of 200 ± 50 Lux, the pixels or dots seen by employees with naked eyes are always bright, and the bright spot is checked under the black screen
Scotoma		A single sub-pixel (or red, or green, or blue) of one pixel is called a point; A dark point is defined as a point that is not bright in a single sub-pixel seen with naked eyes in a 100% white picture under the environment of 200 ±50 Lux.
Dark spot - two connection		Two adjacent sub-pixels under the magnifying glass are not bright at the same time (horizontal, vertical and oblique)
Dark Spot - Three Links		The adjacent R, G and B sub-pixels under the magnifying glass are not bright at the same time (horizontal, vertical and oblique)
CG monomer area division		AA: Front visible area, black ink internal area; A: Black ink area; B: Cover plate edge; The front defect that runs through the AA area and the A area shall be judged according to the specification of the strictest area, and the back defect shall be judged according to whether the AA area is visible.
Foreign matter highlights	-	Due to the foreign matter in the polarizer, the phenomenon that appears as a bright spot is called a foreign matter bright spot

point defect		There are bright spots and black spots in local positions, including but not limited to the internal dirt of the screen itself, pinholes, serrations, concave-convex spots, color spots, tiny bubbles, white spots, stains on the fitting of the polarizer, poor polarizer itself and other spot-like defects. Point defects are judged by diameter.
Linear defect		Linear impurities in the screen, including filaments, fibers, polarizer fitting impurities in the screen, and scratches on the surface of polarizer, etc. Linear defects are judged by length and width. Sensible scratch: also known as hard scratch, is a deep scratch on the surface, which is felt by hand. Senseless scratch: also known as fine scratch, no deep scratch on the surface, no feeling when touching.
Serrated defect		W: Distance from sawtooth crest to trough
Edge collapse/angle collapse		In the process of screen production, especially in the process of molding and cutting, the small glass missing at the glass edge is caused. X direction: parallel to FOG Pad or glass edge; Y direction: perpendicular to FOG Pad or glass edge; Z direction: screen thickness direction; T：The thickness of single-layer glass;
Pitting	-	In the unit area of 10mm * 10mm, the defect point with D ≤ 0.1mm, DS ≥ 2mm, and the number N ≥ 5. If the customer has other requirements, follow the customer's requirements.

Dirty	-	Including handprints, oil stains, fingerprints, stains, white fog and other undesirable phenomena. It is divided into erasable dirt and non-erasable dirt. Use a dust-free cloth dipped in alcohol, which can not be erased as non-erasable dirt. Wipable dirt is determined as follows: A. Dry dust-free cloth can be directly erased; B. Wipe with clean cloth dipped with anhydrous alcohol Press the alcohol-stained dust-free cloth on the dry dust-free cloth twice to absorb excess alcohol; Wipe back and forth with a dust-free cloth twice, and the dirt can be removed.

12.2 Sampling Procedures for Each Item Acceptance Table

Critical Defect (CR): any defect that directly or indirectly affects human health and safety, or the function of the product is lost.

Major Defect (MA): directly or indirectly affect the product function, or make part of the product function lost, and other customers do not acceptable defects.

Minor Defect (MI): appearance defect that does not affect product function and can be accepted by customers.

Defect Type	Sampling Procedures	AQL
Critical Defect (CR)	Take the normal inspection solution of the sampling plan of GB/T2828.1-2012 Inspection levelⅡ	0.065
Major Defect (MA)	Take the normal inspection solution of the sampling plan of GB/T2828.1-2012 Inspection levelⅡ	0.65
Minor Defect (MI)	Take the normal inspection solution of the sampling plan of GB/T2828.1-2012 Inspection levelⅡ	1.0

12.3 Telecommunications Inspection Item

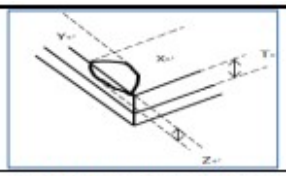
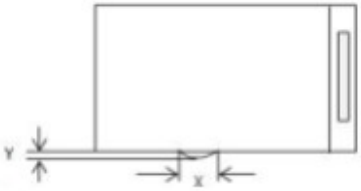
category	NO.	Inspection items	Inspection specification	test mode	defect type
	1	Display exception	not allow	visual	CR

Poor function	2	No display	not allow	visual	CR
	3	The picture flickers	not allow	visual	MA
TP function	4	TP test NG	not allow	visual	MA
Dot	5	Bright dot	not allow	visual	MI
	6	Partial Bright dot	ND6% or reference limit sample	visual	MI
	7	Dark dot	1.D≤0.15mm, ignored; 2.0.15mm < D≤ 0.2mm, DS ≥ 10mm, N ≤ 10; 3.D > 0.2mm,not allowed;	Visual inspection, Flinka	MI
Line	8	Bright line	not allow	visual	MA
	9	Dark line	not allow	visual	MA
	10	Slightly bright line	not allow	visual	MA
Mura	11	horizontal mura	No control under W64/127 screen; The 4%ND Filter on the 255 screen determines that the invisible is OK and the visible is NG.	Visual ND Filter/limit sample	MI
	12	vertical mura	No control under W64/127 screen; The 4% ND Filter on the 255 screen determines that the invisible is OK and the visible is NG.	Visual ND Filter/limit sample	MI
	13	White spot	No control under W64/127 screen; The 4% ND Filter on the 255 screen determines that the invisible is OK and the visible is NG.	Visual ND Filter/limit sample	MI
	14	Black spot	No control under W64/127 screen; The 4% ND Filter on the 255 screen determines that the invisible is OK and the visible is NG.	Visual ND Filter/limit sample	MI
	15	Color mura	4% ND Filter in W64/255 screen determines that the invisible is OK and the visible is NG	Visual ND Filter/limit sample	MI

	16	snowflake	No control under W64/127 screen; The 4% ND Filter on the 255 screen determines that the invisible is OK and the visible is NG.	Visual ND Filter/limit sample	MI
	17	Twill mura	No control under W64/127 screen; The 4% ND Filter on the 255 screen determines that the invisible is OK and the visible is NG.	Visual ND Filter/limit sample	MI
	18	Newtonian ring	No control under W64/127 screen; The 4% ND Filter on the 255 screen determines that the invisible is OK and the visible is NG.	Visual ND Filter/limit sample	MI
	19	Uneven transition	Reference homogeneity standard to assist in judgment; The 4% ND Filter in the W64/255 screen determines that the invisible product is OK and the visible product is NG.	Visual ND Filter/limit sample	MI
	1、 Mura all specify the screen judgment. For example, if the ELA mura judgment standard is 255, the ELA mura will only be judged on the W255 screen. 2、 Other types of mura have a low adverse effect rate and low incidence. According to the 4% ND Filter in the W64/255 screen, the invisible products are OK and the visible ones are NG.				
Dot/line of foreign material	20	Dot/line defects (foreign material, black white dot, scratch, bubble, etc.)	Same point/line specifications	Visual inspection/Flinka	MI

12.4 Appearance Inspection Item

NO.	Inspection items	Surface Area	Inspection specification	test mode	defect type
1	Broken glass	AA/OA	not allow	visual	MA
2	crack	AA/OA	not allow	visual	MA
3	Edge collapse/corner	AA/OA	1. Y ≤ 0.15mm, X and N are ignored; 2. 0.15 < Y ≤ 0.4mm, X ≤ 2mm, N is ignored; 3. Y > 0.4mm, not allowed; 4. Z ≤ t, without damage to Frit body;	Visual inspection, Flinka	MI

					
4	flange	AA/OA	1. Y ≤ 0.2mm, X is uncontrolled; 2. Y > 0.2mm, not allowed; 	Visual inspection, Flinka	MI
5	Glass warp	Whole area	 The product is placed horizontally on the front and back, and the lifting height at one end (plug gauge) ≤ 0.6mm	Visual inspection, Flinka	MI
6	Pin dirty	Bongding area	No control	visual	MI
7	Pin scratch	Bongding area	Scratches and whitening are found by visual inspection, and need to be rechecked with a microscope. The broken lead is not allowed, and the overlap is not allowed Note: CT pad area and pin non-bonding area are not controlled	visual	MI
8	PF film bump	LTPS	Touch is not allowed	visual	MI
9	PF film pinholes/pits	LTPS	No control	visual	MI
10	PF film scratch	LTPS	1. No scratch, no control; Scrape through, L<10mm; 2. The film shall be scraped through the exposed glass surface, referring to the lack of glue of PF film;	Visual inspection, Flinka	MI
11	PF film lacks glue	LTPS	50> 5mm, W>5mm not allowed	Visual inspection, Flinka	MI
12	PF membrane is dirty	LTPS	Wipable dirt needs to be wiped, and non-wipe dirt refers to the color difference of PF film;	visual	MI
13	PF film overflow	LTPS	1. Edge overflow W<0.2mm, acceptable; 2. W>0.2mm, not allowed;	Visual inspection, Flinka	MI

14	Color difference/stain (no convex touch)	LTPS	No control					visual	MI
15	PF film gluing offset	LTPS	1. Step area is not allowed; 2. Except for the step area, the rest shall be controlled by 0.5 ±0.2mm;					Visual inspection, Flinka	MI
16	Screen body is dirty	LTPS	1. The front can be wiped and the dirt can be wiped, and the polarizer of the dirt cover cannot be wiped; 2. The back is not controlled;					visual	MI
17	point defect	AA	D (mm)	DS (mm)	Acceptable number			Visual inspection, Flinka	MI
			D≤ 0.15mm	/	Ignore				
			0.15mm< D≤0.2mm	DS≥10	N≤10				
18	Linear defect/foreign matter linear/non-inductive scratch	AA	W (mm)	L (mm)	DS (mm)	Acceptable number		Visual inspection, Flinka	MI
			W≤ 0.03	L≤5	≥10	ignore			
			0.03< W≤ 0.05	L≤2	≥10	ignore			
			0.03< W≤ 0.05	2 < L≤5	≥10	N≤4			
			W>0.05	-	/	Not allowed			
			-	L>5	/	Not allowed			
19	Point/Line defects	Camera hole area/Blind hole area	D(mm)		Acceptable number			Visual inspection, Flinka	MI
			D≤0.15		ignore				
			0.15 < D≤0.2		ignore				
			D>0.2						
20	Newton rings（Blind hole area）	Camera hole area/Blind hole area	Not control					Visual inspection	MI
21	offset	Camera hole	The metal ring extends inward 0.1mm ,ingore					Visual inspection	MI

		area/Blind hole area			
22	Blind hole color bias(same color)	Camera hole area/Blind hole area	Functional requirements such as transmittance and PV value are met,not control appearance	Visual inspection	MI
23	Protective film scratch	Whole area	No control under no hurt boby	Visual inspection	MI
24	Protective film starved/overflow glue/burr	Whole area	No control under no hurt boby	Visual inspection	MI
25	Dirt inside the protective film	Whole area	Not allowed	Visual inspection	MI
26	Easy to tear	Cover front	Function is invalid, damaged, leaked not allowed Wrinkles, bumps, dirt, punching bad, burr, overflow glue is not controlled	Visual inspection	MI
27	Polarizer edge overflow	AA	W≤0.35mm , Not control; W>0.35mm, Not allowed.	Visual inspection, Flinka	MI
28	Polarizer concave convex point	AA	convex point: D≤0.2mm or refer to limit sample concave point: D≤3mm, DS≥10mm, N≤3 or refer to limit sample	Visual inspection, Flinka	MI
29	Polarizer fold / indentation	AA	Does not affect the display as OK or refer to limit sample;	Visual inspection	MI
30	Polarizer chromatism	AA	No control	Visual inspection	MI
31	IC chip	IC	Not allowed	Visual inspection	MI
32	FPC body defect	FPC	1. The parts on the FPC must be consistent with the product BOM table, and there are incorrect, multiple, or missing parts, which are not allowed; Polarities such as capacitors and inductors should not be soldered backwards or crooked; 2. FPC scratches/scratches are based on the absence of exposed copper; 3. Creases/Indentations: Indentations in the circuit area should not cause the back of the	Visual inspection	MI

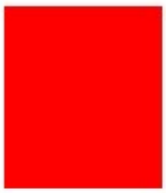
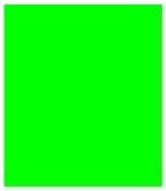
			covering film to turn white; Non line area indentation should not cause FPC damage 4. Except for the golden finger. FPC foreign object: a. Spot shape: D ≤ 0.5mm, N ≤ 3; b. Linear: length and width ≤ 0.3 * 5mm;		
33	FPC gold finger defect	Golden Finger Region	1. Golden finger cracking: The length and width of the crack/damage at the top of the golden finger ≤ the line width; 2. Gold finger copper leakage: W ≤ 1/3 line width, L ≤ line width, unlimited quantity 3. Gold finger gap W1 ≤ 1/3 line width W, length L1 ≤ 1/2 line width W, unlimited quantity, all of the above conditions are met and allowed; 4. Gold finger pressure/scratch should not expose copper, there should be no unevenness, and there should be no depth visible to the naked eye, which does not affect assembly and is acceptable; 5. Gold fingers should not have sharp creases or dead folds; 6. FPC gold fingers should not have oxidation, blackening, burns, or browning;	Visual inspection	MI
34	connector	connect or	There should be no tin or residual solder beads on the connector, and there should be no tin connection on the connector pins; PIN deformation shall be controlled within 0.05mm; Does not affect the lighting function; Visual inspection of pin breakage, pin detachment, and deformation of the outer frame is not allowed;	Visual inspection	MI
35	Insulating tape	Bondin g area	There must be no obvious wrinkles or bubbles	Visual inspection	MI
		Compo nent area	1. Scratches and glue splashes are uncontrollable; 2. Do not wipe dirt or dirt; 3. The offset of the insulation tape should not exceed the edge of the product, and other requirements should be determined based on the drawing; 4. Burr edges, no control over glue overflow;		

			5. Damaged, incomplete, or missing labels are not allowed;		
36	Composite tape	All	1. It is not allowed for the composite tape to leak out of the edge of the screen body; 2. Folding of composite tape, light leakage during assembly, or affecting assembly and thickness are not allowed; 3. Damaged composite tape is not allowed; 4. The size of the composite tape cutting defect does not meet the requirements of the drawing and cannot be controlled; 5. Composite tape should not be wiped with dirt or foreign objects, and foreign objects should follow the dotted line standard; 6. The burrs of the composite tape should not exceed the edge of the screen body, regardless of control; 8. Composite adhesive tape with no control over glue splashes or overflow; 9. Composite tape bubbles: D ≤ 5mm, N not included; 10. Composite tape bumps: acute angle bumps D ≤ 0.3mm, N ≤ 3; Smooth concave convex points D ≤ 0.8mm, N ≤ 3; 11. Composite tape foreign object (foreign object between copper foil and blue film): D ≤ 0.3mm, N ≤ 3; 12. Edge sawtooth of composite tape: 0.5 * 3mm, N ≤ 3; 13. The color difference of the protective film in the composite tape is not controlled; 14. Copper foil indentation and dead bending in composite tape are not allowed, which does not affect assembly and thickness control; Or reference limit sample; 15. No control of foreign objects/dents in copper foil in composite tape;	Visual inspection	MI
37	OCA overflow	All	Not allowed within AA area; Externally visible: Control standard ≤ 0.15mm	Visual inspection	MI

38	Sealing glue	Pin	1. Broken adhesive is not allowed, and the circuit cannot be exposed. 2. The thickness of the colloid shall not be higher than the POL surface. 3. Bubble diameter<1mm. 4. Other: According to the drawings and work instructions.	Visual inspection	MI
39	Conductive cloth	All	1. Conductive cloth dirt: D ⩽ 5mm, N ⩽ 2; 2. Conductive cloth bubbles: D ⩽ 2mm, N ⩽ 2; 3. Conductive cloth foreign object: D ⩽ 1mm, N ⩽ 3; 4. Folding of conductive fabric: N ⩽ 2;	Visual inspection	MI
40	Copper foil	All	Copper foil sticking is not allowed to leak out of the edge of the screen body; Abnormal color of copper foil refers to standard samples/sealed samples, and damage is not allowed. Soft scratches on the surface are not controlled.	Visual inspection	MI
41	QR code	QR code	It is not allowed to be unable to scan or difficult to scan (recognition can only be achieved after three consecutive scans), with a clear appearance, no blurring, missing printing, and other defects	Visual inspection	MI
42	Package	Other	Products should put into the anti-static trays, with non-overlapping, and the trays should be staggered placed.	visual	-
			Different products cannot be mixed into the same inner package.		
			The package should not have obvious deformation or breakage .The printing labels type and quantity are correct.		
			The package should have QC signature. ROHS label is needed if the product is under ROHS control.		
43	Boundary dimension NG	Other	It is not allowed to exceed the dimensional tolerance required by the specifications and drawings	Calipers, measuring instruments	-

12.5 Inspection picture library

Serial number	picture	Picture name	Mainly judged as defective	remarks

1		W_ GRAD(64) 64 gray scale	Point/line type, foreign matter point/line, mura type	/
2		W_ GRAD(128) 128 gray scale	Point/line type, foreign matter point/line, mura type	/
3		WHITE white	Point/line type, foreign matter point/line, mura type	/
4		Black black	Bright spot, bright line, dark mura	/
5		RED red	Point type, line type, foreign matter point/line	/
6		GREEN green	Point type, line type, foreign matter point/line	/
7		BLUE blue	Point type, line type, foreign matter point/line	/

Note: The actual sequence and lock seconds of the screen can be adjusted according to the customer's requirements and the needs of the factory.

13. PRECAUTIONS FOR USE OF AMOLED MODULES

13.1 Handling Precautions:

13.1.1 The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from height.

13.1.2 Do not press down the screen or the adjoining areas too hard because the color tone may be shifted.

13.1.3 The polarizer covering the display surface of the AMOLED module is soft and easily scratched. Handle this polarizer carefully.

13.1.4 If the display surface is contaminated, blow on the surface and gently wipe it with a soft dry cloth. If it is still not completely clear, moisten the cloth with ethyl alcohol.

13.1.5 Solvents may damage the polarizer. Do not use water, ketone or aromatic solvents except ethyl alcohol.
Do not attempt to disassemble the AMOLED Module.

13.1.6 If the logic circuit power is off, do not apply the input signals.

13.1.7 To prevent destruction from static electricity, be careful to maintain an optimum working environment.

13.1.8 Be sure to make yourself in contact with the ground when handling with the AMOLED Modules.

13.1.9 Tools required for assembly, such as soldering irons, must be properly ground.

13.1.10 To reduce the generation of static electricity, do not conduct assembly or other work under dry conditions.

13.1.11 To protect the display surface, the AMOLED Module is coated with a film. Be careful when peeling off this protective film, because static electricity may generate.

13.2 Storage Precautions:

13.2.1 When storing the AMOLED modules, be sure that they are not directly exposed to the sunlight or the light of fluorescent lamps.

13.2.2 The AMOLED modules should be stored under the storage temperature range. If the AMOLED modules will be stored for a long time, the recommended condition is:
Temperature: 0℃~40℃ Relatively humidity: ≤80%

13.2.3 The AMOLED modules should be stored in the room without acid, alkali or harmful gas.

13.3 Transportation Precautions:

13.3.1 The AMOLED modules should not be suffered from falling and violent shocking during transportation. Besides, excessive press, water, damp and sunshine, should be avoided.